



# Shicong Wang

## Education

### The Ohio State University

Columbus, OH

Computer Science and Engineering

Cumulative GPA: 3.8

- Dean's list: summer 2020; spring2020; autumn 2019

### Shanghai Institute of Technology

Shanghai

Mechanical Engineering

Cumulative GPA: 3.5

- First prize scholarship: spring 2019; autumn 2018
- Second prize scholarship: spring 2018; autumn 2017

## Experience

### The Ohio State University - Grader

01/2020 - 05/2020

- Documented inspections, assignments and task completion to comply with course policies;
- Proactive in using good judgment in the handling of student concerns;
- Develop homework and lab materials;
- Communicated effectively with other graders;

### The Ohio State University - Game Designer

09/2020 - 11/2020

User vs AI Tic-Tac-Toe Game

- JavaScript implementation;
- Various difficulty levels for different methods of implementation;
- Different behaviors with different algorithms;

### University of Cambridge – Cambridge Winter Exchange Programme

01/2018 - 02/2018

Final grade: 98/100

- Developed insights into engineering philosophy;
- Increased transferable skills; develop the capacity for critical thinking

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## Skills

- Java
- Ruby
- HTML/JavaScript/CSS
- MATLAB
- VBA
- Solidworks/CAD
- MS Office

## Other Experience

- Member: Tau Beta Pi
- Designer: Bug World complier
- Designer: eight puzzle game in JavaScript
- Designer: windshield cover design
- Designer: network package forwarding demo
- Designer: set game in Ruby
- Mentor: OHI/O High School
- Volunteer: Shanghai Gongli Hospital
- Student Assistant: Vice-Dean of SIT Engineering College

## Attributes

- Excellent learner
- Good teammate
- Quick mind
- Perseverance
- Extroversion